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JH Rei <u>P67426USO</u> Tol	day's Date <u>March 19, 2004</u>
Serial/Patent No. 10 / 017 , 318	
Auplicant, Patentee, Assignee <u>Joon Ki HONG, et al.</u>	
Filing Date/Patent Date December 18, 2001	
The following has been received in the U.S. Patent & Trademark Office on the date stamped hereon:	
pp. Specification &Slaims	B ☐ Response to Office Action
☐ Combined Declaration, Power of Attorney ☐ P	□ Disclosure Statement-IDS
☐ Preliminary Amendment	Copies of References
☐ Rule 53 (b) Application MAR 1 9 2004	Request for Refund
☐ Rule 53 (d) /RCE Application	Request for Corrected Filing Receipt
☐ Claim to Priority and Certified Copy	Petition for XOT
☐ Substitute ☐ Subsequent Declaration Range AND	☐ Notice of Appeal/Brief
☐ Maintenance Fee	☐ Sequence Listing
☐ Drawings SheetsFormalInformal	☐ Issue Fee Transmittal
☐ Assignment/Change of Name	Other Amendment under 37 CFR
☐ Small Entity Declaration	1.312
☐ Check for \$	JACOBSON HOLMAN PLLC
	400 SEVENTH STREET, N.W.
JH 11/01 DUE DATE	WASHINGTON, D.C. 20004
Person filing YSY /K-/C	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Confirmation No.: 8219

Joon Ki HONG, et al.

Allowed: March 8, 2004

Serial No.: 10/017,318

Group Art Unit: 2814

Filed: December 18, 2001

Examiner: HA, NATHAN W

For: STACK CHIP MODULE WITH ELECTRICAL CONNECTION AND ADHESION

OF CHIPS THROUGH A BUMP FOR IMPROVED HEAT RELEASE CAPACITY

(As Amended)

AMENDMENT UNDER 37 CFR 1.312

MAIL STOP ISSUE FEE Commissioner for Patents, PO Box 1450, Alexandria, VA 22313



March 19, 2004

Sir:

It is respectfully requested that the following be entered pursuant to the provisions of 37 CFR 1.312:

On the Notice of Allowance and Issue Fee Due mailed March 8, 2004, the title of the invention, i.e. - STACK CHIP MODULE - is incorrect.

In Office Action dated January 24, 2003, Examiner accepted Applicant's Amendment to title dated December 24, 2002 as descriptive and acceptable.

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Accordingly, please correct the title of the invention to read as follows:

-- STACK CHIP MODULE WITH ELECTRICAL CONNECTION AND ADHESION OF CHIPS THROUGH A BUMP FOR IMPROVED HEAT RELEASE CAPACITY --.

If a Petition for Extension of Time is necessary and the Petition and/or the check is not enclosed, this will act as the Petition and applicant herewith petitions the Commissioner to extend the time for response and charge any fees necessary under 37 CFR 1.17 (a)(1)-(5) to Deposit Account No. 06-1358.

The Commissioner is also authorized to charge payment of any other additional fees associated with this communication or credit any overpayment to Deposit Account No. 06-1358. A duplicate copy of this sheet is attached.

It is requested that entry of the above amendment be transmitted to the undersigned attorney.



Serial No. 10/017,318 Atty. Docket No. P67426US0

Respectfully submitted,

JACOBSON HOLMAN PLLC

Bv:

Yoon S. Ham, Reg. No. 45,307

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Atty. Docket: P67426US0

YSH:kyc

